

### General Description

The Sanrise SRC60R017FB is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC60R017FB break down voltage is 600V and it has a high rugged avalanche characteristics. The SRC60R017FB is available in TO-247 package.

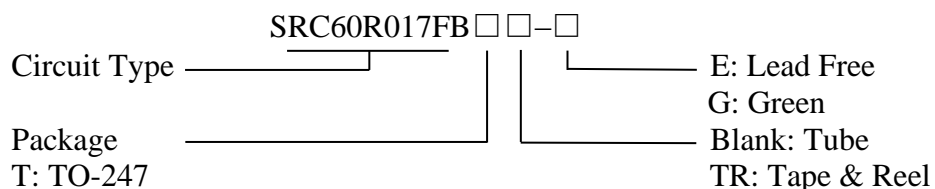
### Features

- Ultra Low  $R_{DS(ON)} = 17m\Omega @ V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g=291nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved

### Application

- EV Charger
- Sever / Telecom Power

### Ordering Information



### Symbol

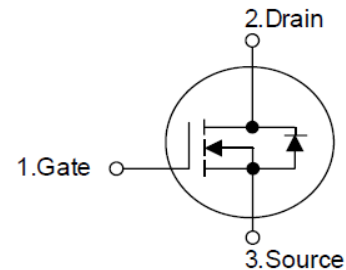


Figure 1 Symbol of SRC60R017FB

### Package Type



Figure 2 Package Types of SRC60R017FB

Package	Part Number		Marking ID		Packing Type
	Lead Free	Green	Lead Free	Green	
TO-247	SRC60R017FBT-E	SRC60R017FBT-G	SRC60R017FBTE	SRC60R017FBTG	Tube

### Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		$V_{DSS}$	600	V
Gate-Source Voltage (static)		$V_{GSS}$	±20	V
Gate-Source Voltage (dynamic), AC $f > 1\text{Hz}$		$V_{GSS}$	±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	120	A
	$T_C = 125^\circ\text{C}$		54	
Pulsed Drain Current (Note 2)		$I_{DM}$	360	A
Avalanche Energy, Single Pulse (Note 3)		$E_{AS}$	600	mJ
Avalanche Energy, Repetitive (Note 2)		$E_{AR}$	0.6	mJ
Avalanche Current, Repetitive (Note 2)		$I_{AR}$	9.0	A
Continuous Diode Forward Current		$I_S$	120	A
Diode Pulse Current		$I_{S,PULSE}$	360	A
MOSFET $dv/dt$ Ruggedness, $V_{DS} \leq 480\text{V}$		$dv/dt$	80	V/ns
Reverse Diode $dv/dt$ , $V_{DS} \leq 480\text{V}$ , $I_{SD} \leq I_D$		$dv/dt$	50	V/ns
Operating Junction Temperature		$T_J$	150	°C
Storage Temperature		$T_{STG}$	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3.  $I_{AS} = 9.0\text{A}$ ,  $V_{DD} = 60\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

### Thermal characteristics

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-247	$R_{thJC}$			0.21	°C /W
Thermal resistance, Junction-to-Ambient	TO-247	$R_{thJA}$			62	°C /W

## Electrical Characteristics

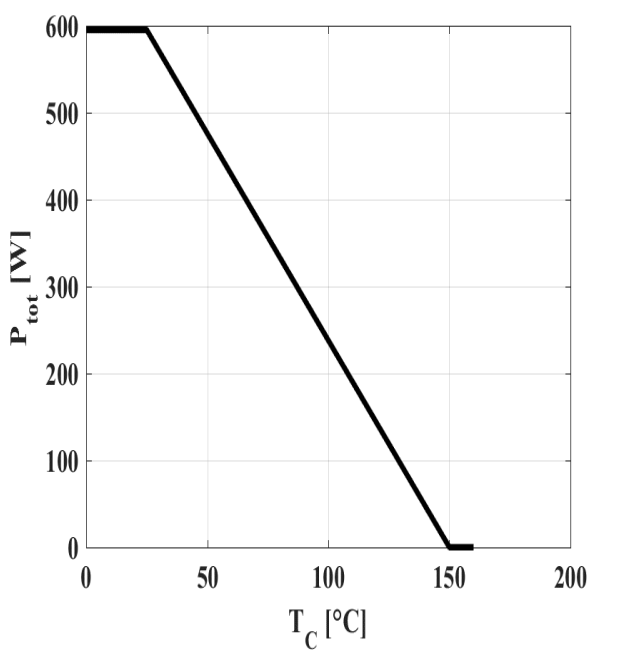
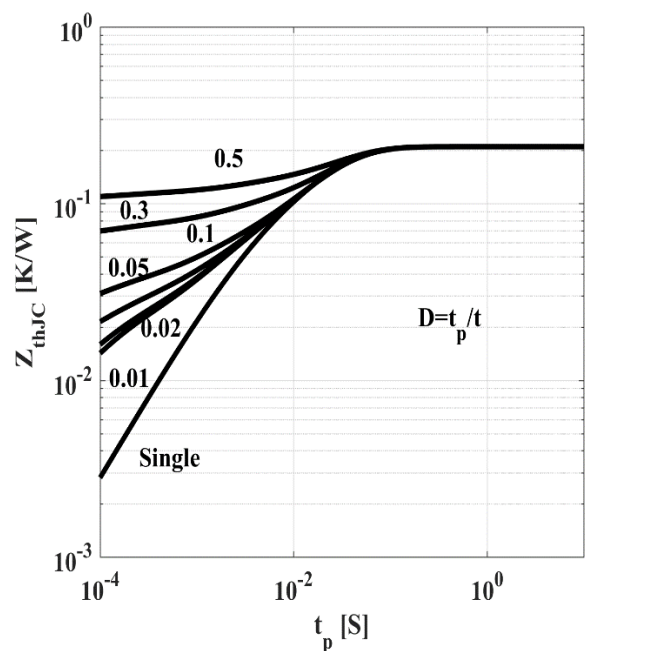
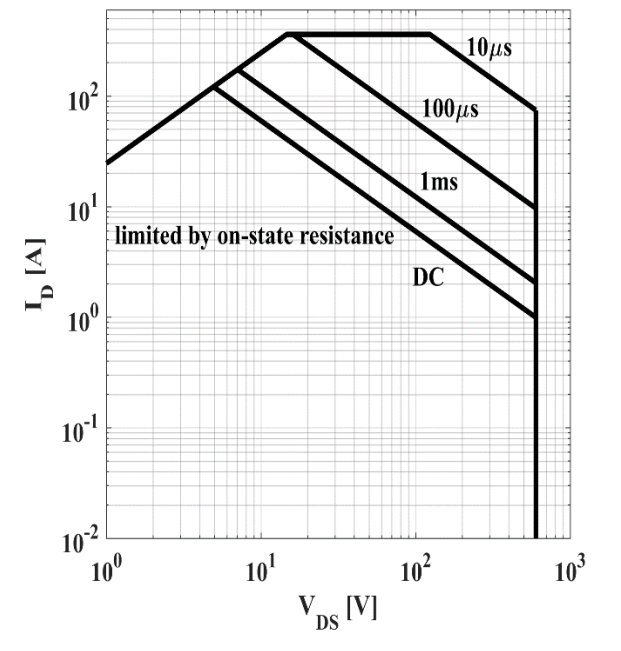
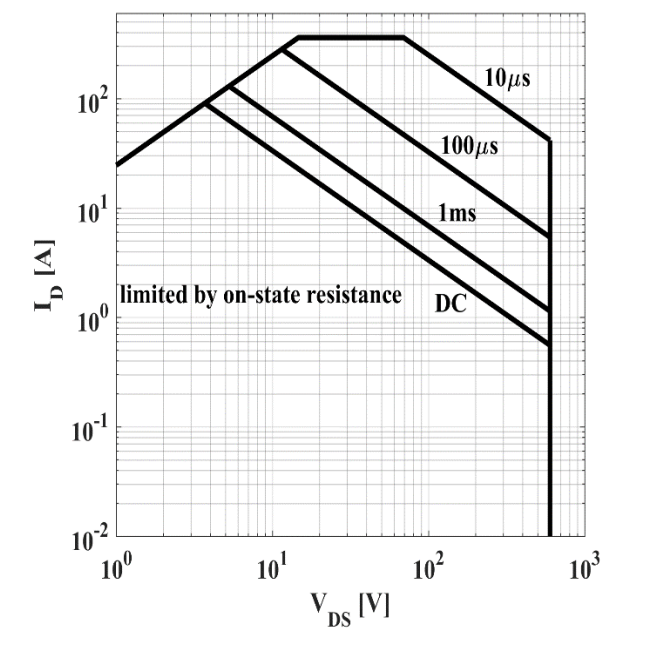
$T_J = 25^{\circ}\text{C}$ , unless otherwise specified.

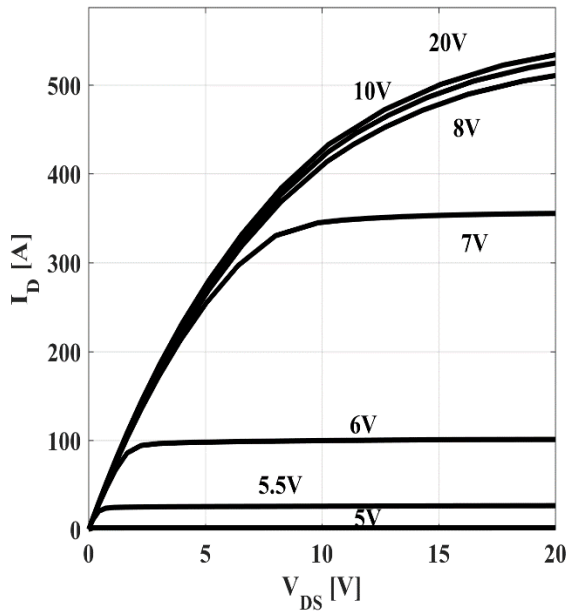
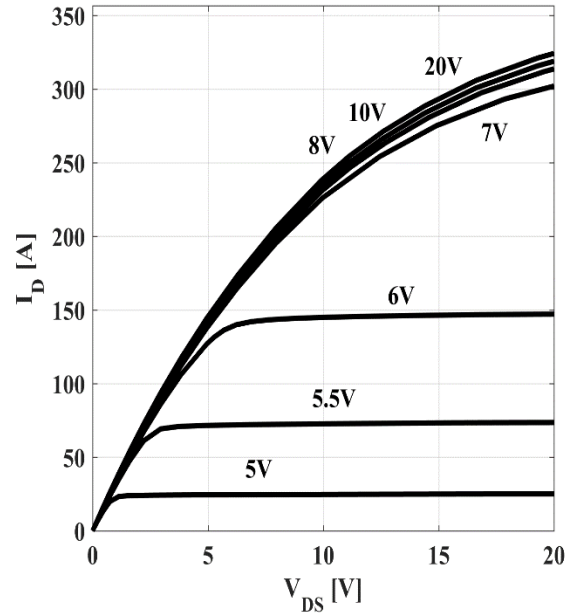
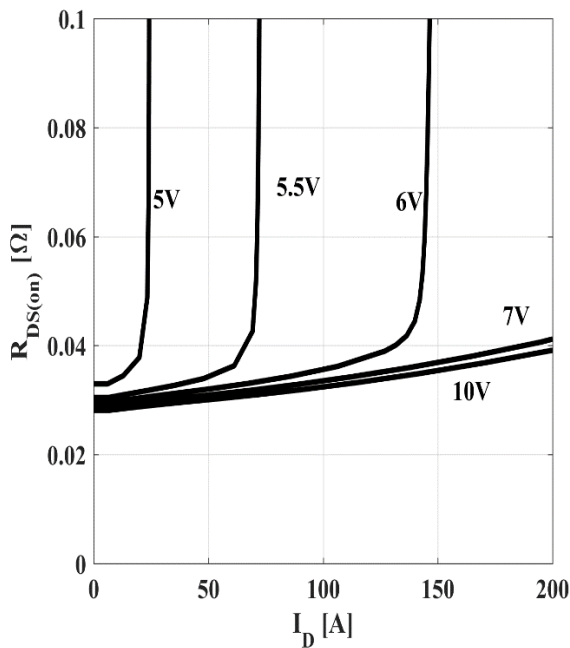
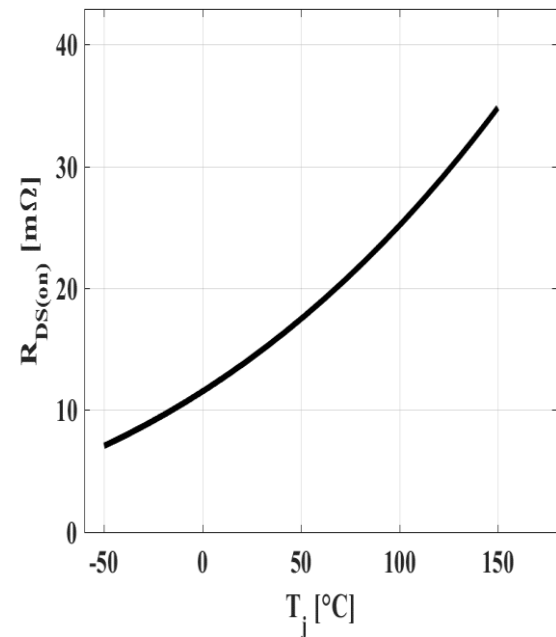
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
<b>Statistic Characteristics</b>							
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	600			V	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=600V, V_{GS}=0V$			10	$\mu A$	
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=30V, V_{DS}=0V$			200	nA	
	Reverse	$I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$			-200		
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=2.9mA$	3.0	4.0	5.0	V	
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=40A$		14.3	17	$m\Omega$	
Gate Resistance	$R_G$	$f=1MHz, \text{Open Drain}$		1.0		$\Omega$	
<b>Dynamic Characteristics</b>							
Input Capacitance	$C_{ISS}$	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		12.7		nF	
Output Capacitance	$C_{OSS}$				546		pF
Reverse Transfer Capacitance	$C_{RSS}$				2.0		pF
Effective output capacitance, energy related <sup>NOTE5</sup>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 480V$		291		pF	
Effective output capacitance, time related <sup>NOTE6</sup>	$C_{O(tr)}$			237			
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=60A, R_G=1.8\Omega, V_{GS}=10V$		30		ns	
Rise Time	$t_r$			27			
Turn-off Delay Time	$t_{d(off)}$			125			
Fall Time	$t_f$			6			
<b>Gate Charge Characteristics</b>							
Gate to Source Charge	$Q_{gs}$	$V_{DD}=480V, I_D=60A, V_{GS}=0 \text{ to } 10V$		73.6		nC	
Gate to Drain Charge	$Q_{gd}$			120			
Gate Charge Total	$Q_g$			291			
Gate Plateau Voltage	$V_{plateau}$			5.8		V	
<b>Reverse Diode Characteristics</b>							
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=40A$		0.85	1.1	V	
Reverse Recovery Time	$t_{rr}$	$V_R=400V, I_F=40A, dI_F/dt=100A/us$		184		ns	
Reverse Recovery Charge	$Q_{rr}$			1.47		$\mu C$	
Peak Reverse Recovery Current	$I_{rrm}$			16		A	

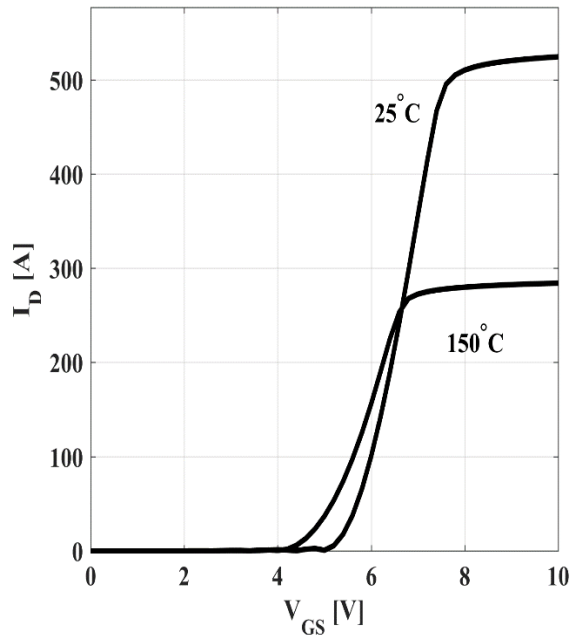
Note:

- $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480V
- $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 480 V

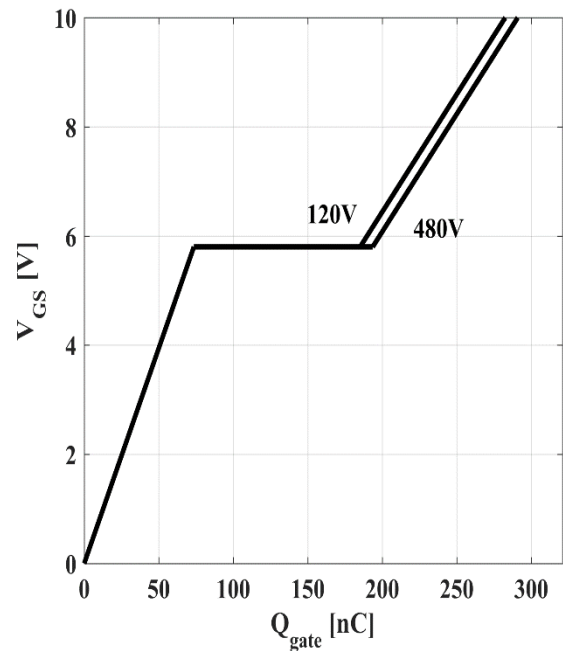
**Typical Performance Characteristics**

<p>Figure 3: Power Dissipation</p>  <p><math>P_{tot} = f(T_c)</math></p>	<p>Figure 4: Max. Transient Thermal Impedance</p>  <p><math>Z_{(th)JC} = f(t_p)</math>; parameter: <math>D = t_p/T</math></p>
<p>Figure 5: Safe Operating Area</p>  <p><math>I_D = f(V_{DS})</math>; <math>T_c = 25^\circ\text{C}</math>; <math>V_{GS} &gt; 7\text{V}</math>; parameter <math>t_p</math></p>	<p>Figure 6: Safe Operating Area</p>  <p><math>I_D = f(V_{DS})</math>; <math>T_c = 80^\circ\text{C}</math>; <math>V_{GS} &gt; 7\text{V}</math>; parameter <math>t_p</math></p>

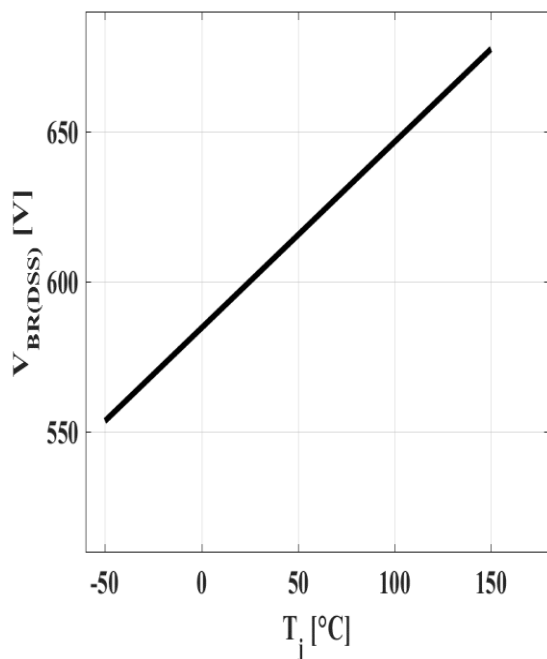
**Figure 7: Typ. Output Characteristics**

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$ 
**Figure 8: Typ. Output Characteristics**

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$ 
**Figure 9: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$ 
**Figure 10: Typ. Drain-Source On-State Resistance**

 $R_{DS(ON)} = f(T_j); I_D = 40\text{A}; V_{GS} = 10\text{V}$

**Figure 11: Typ. Transfer Characteristics**


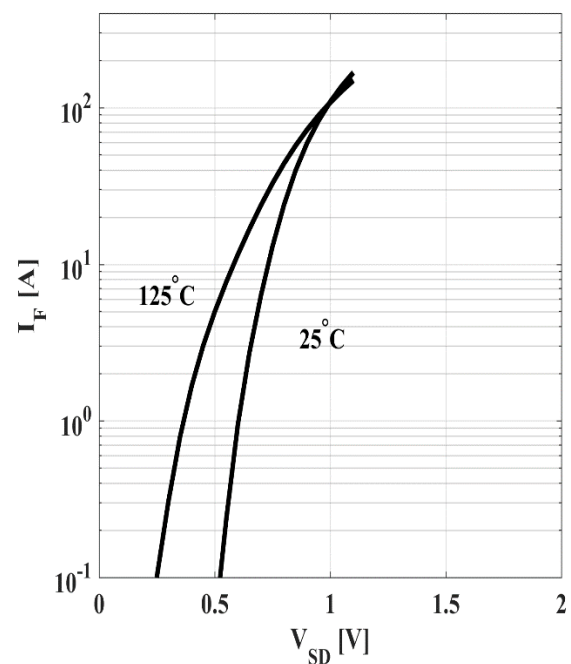
$$I_D = f(V_{GS}); V_{DS} = 20\text{V}$$

**Figure 12: Typ. Gate Charge**


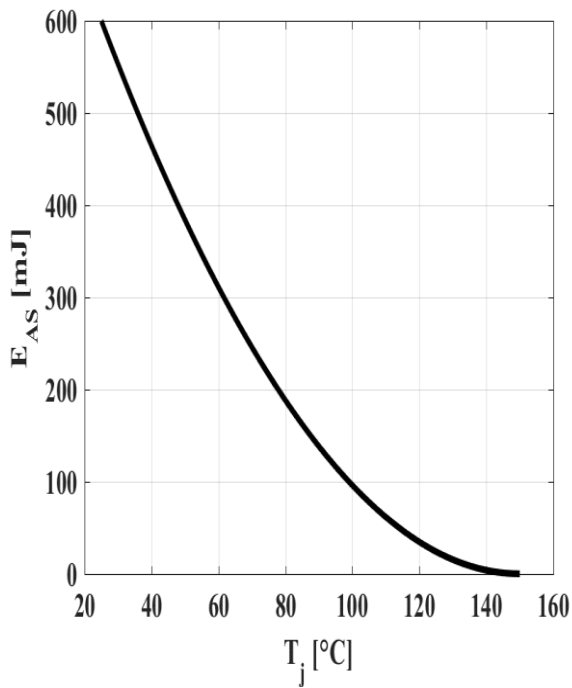
$$V_{GS} = f(Q_{gate}), I_D = 60\text{A pulsed}$$

**Figure 13: Drain-Source Breakdown Voltage**


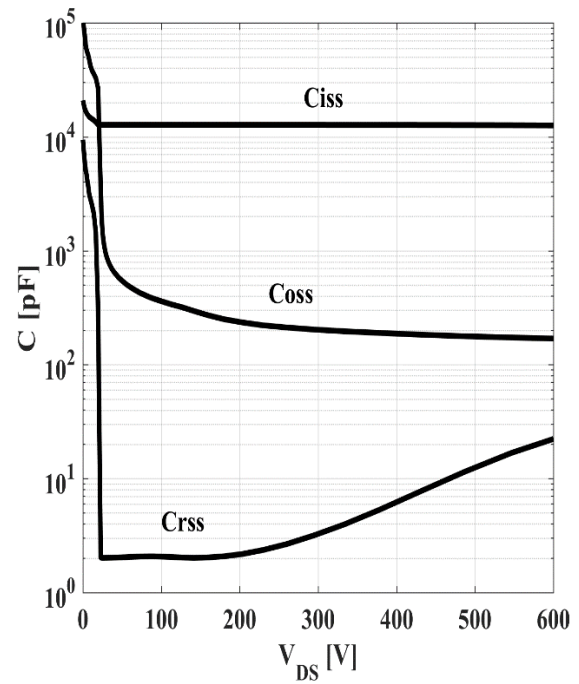
$$V_{BR(DSS)} = f(T_j); I_D = 20\text{mA}$$

**Figure 14: Forward Characteristics of Reverse Diode**


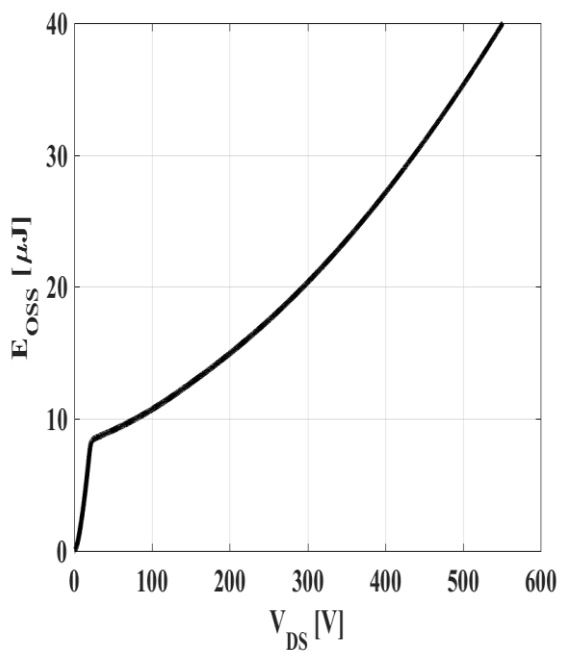
$$I_F = f(V_{SD}); \text{parameter: } T_j$$

**Figure 15: Avalanche Energy**


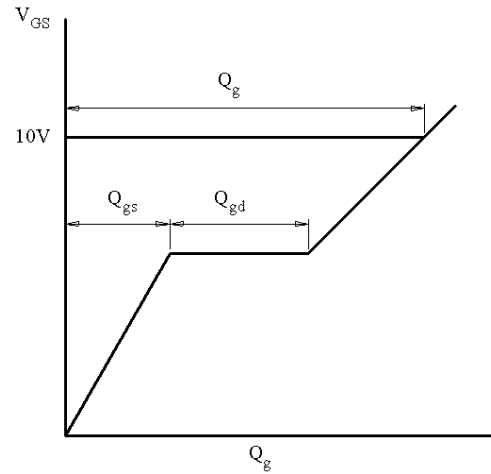
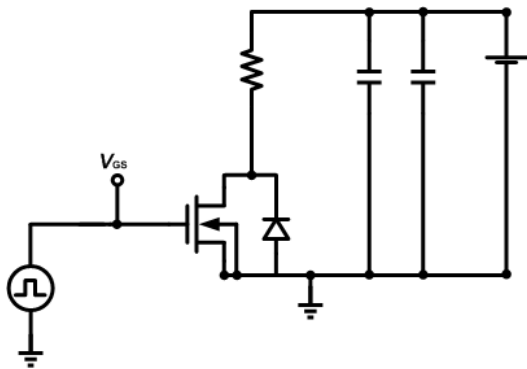
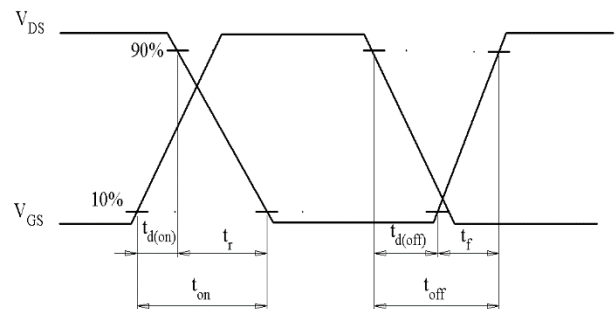
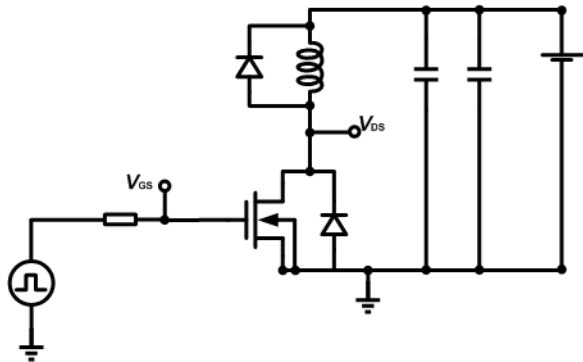
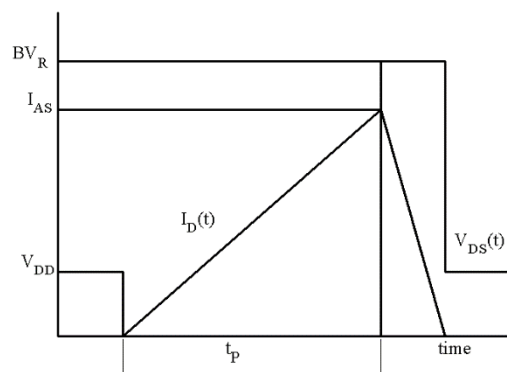
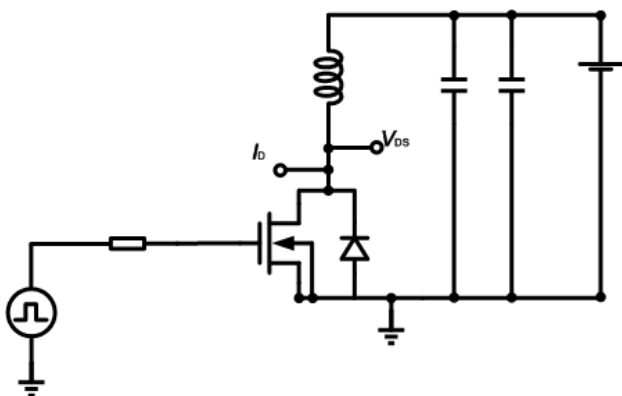
$$E_{AS}=f(T_j); I_D=9.0A; V_{DD}=60V$$

**Figure 16: Typ. Capacitances**


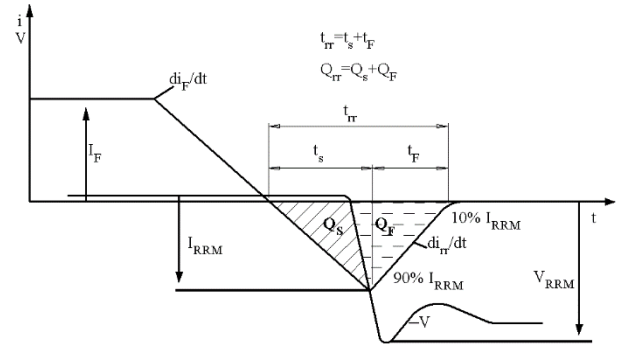
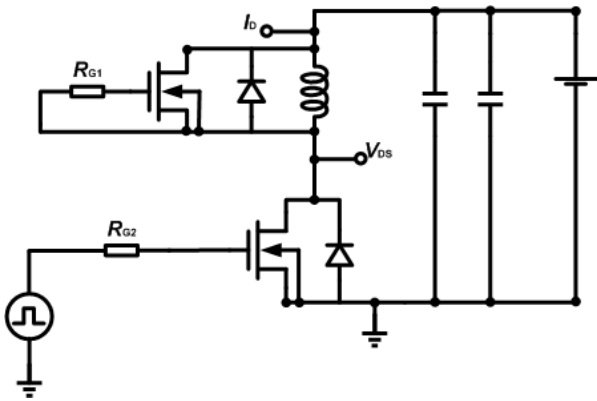
$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

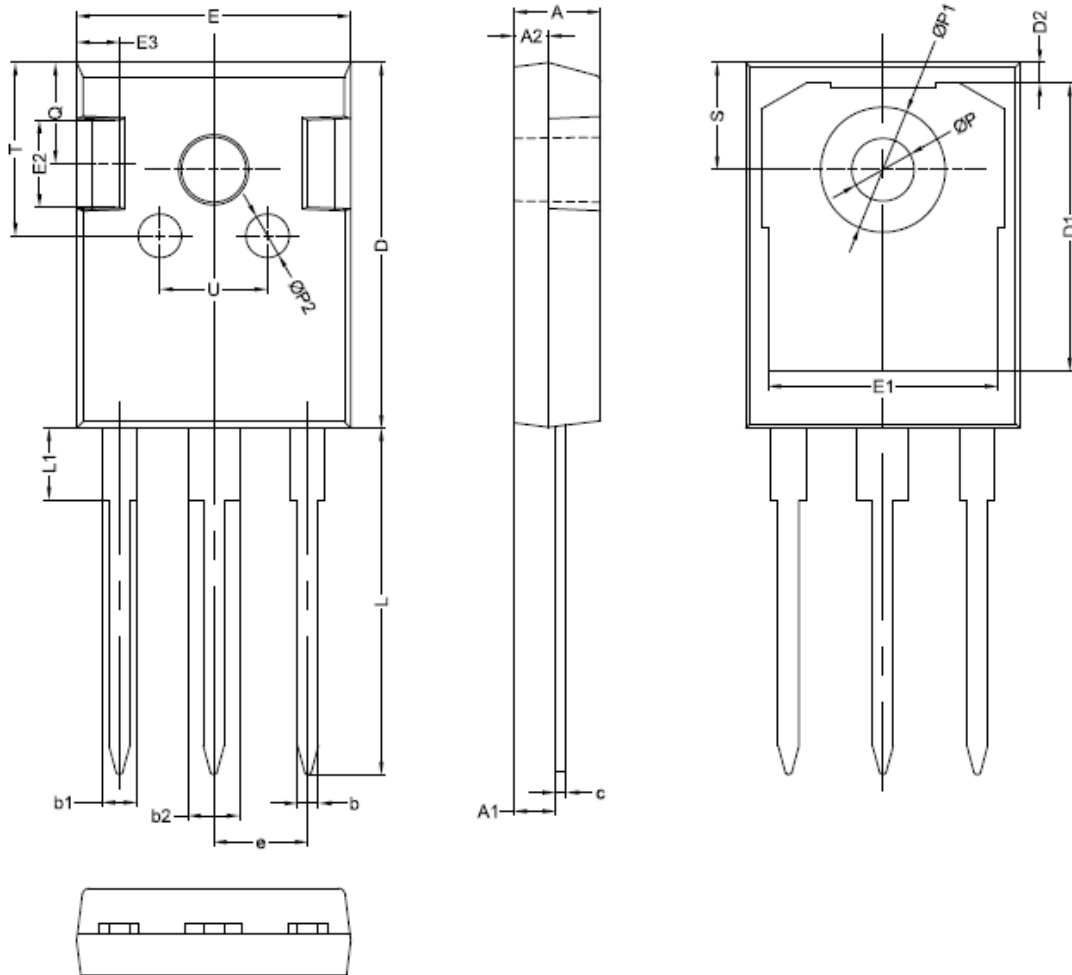
**Figure 17: C<sub>OSS</sub> Stored Energy**


$$E_{OSS}=f(V_{DS})$$

**Test Circuits**
**1. Gate Charge Test Circuit & Waveform**

**2. Switch Time Test Circuit**

**3. Unclaimed Inductive Switching Test Circuit & Waveforms**


**4. Test Circuit and Waveform for Diode Characteristics**



**Mechanical Dimensions**
**TO-247**
**Unit: mm**


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E2	-	5.00	-
A1	2.21	2.41	2.61	E3	-	2.50	-
A2	1.90	2.00	2.10	e	5.44(BSC)		
b	1.10	1.20	1.35	L	19.42	19.92	20.42
b1	-	2.00	-	L1	-	4.13	-
b2	-	3.00	-	P	3.50	3.60	3.70
c	0.55	0.60	0.75	P1	-	-	7.40
D	20.80	21.00	21.20	P2	-	2.50	-
D1	-	16.55	-	Q	-	5.80	-
D2	-	1.20	-	S	6.05	6.15	6.25
E	15.60	15.80	16.00	T	-	10.00	-
E1	-	13.30	-	U	-	6.20	-



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